

	Type	Hits	Search Text
1	BRS	0	257/79,80,82,88,98,100,431,432,433,434 \$.ccls. and wire and (encapsulat\$4 epoxy resin)
2	BRS	1608	257/79,80,82,88,98,100,431,432,433,434 .ccls. and wire and (encapsulat\$4 epoxy resin)
3	BRS	33	257/79,80,82,88,98,100,431,432,433,434 .ccls. and wire and (encapsulat\$4 epoxy resin) and (carrier board substrate) with (chip die ic) adj2 (window area)
4	BRS	38	257/79,80,82,88,98,100,431,432,433,434 .ccls. and wire and (carrier board substrate) with (chip die ic) adj2 (window area)
5	BRS	335	257/79,80,82,88,98,100,431,432,433,434 .ccls. and wire and (carrier board substrate) same (chip die ic) with (cavit\$3 opening hole via)
6	BRS	2	"6874910"
7	BRS	2	"20030052594"
8	BRS	2	"20030189829"
9	IS&R	3	((("6874910") or ("20030052594") or ("20030189829"))).PN.
10	BRS	10	("20020096753"   "5211762"   "5952714"   "6130448"   "6297540"   "6396116"   "6455774"   "6531341"   "6545332"   "6590269").PN.
11	BRS	12	sorg-j-\$.in.
12	BRS	1	kraeuter-g-\$.in.
13	BRS	778	257/666,668,672,676,690,784,786,787.cc ls. and (LED light adj emitting adj2 (diode chip ic die) optical adj2 (chip die ic element))

	DBs	Time Stamp	Comments	Error Definition
1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/08/11 15:52		
2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/08/11 15:54		
3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/08/11 17:05		
4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/08/11 15:57		
5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/08/11 17:01		
6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/08/11 16:09		
7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/08/11 16:09		
8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/08/11 16:09		
9	US-PGPUB; USPAT	2005/08/11 16:10		
10	US-PGPUB; USPAT; USOCR	2005/08/11 16:50		
11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/08/11 17:04		
12	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/08/11 17:04		
13	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/08/11 17:07		

	Type	Hits	Search Text
14	BRS	402	257/666,668,672,676,690,784,786,787.ccls. and (LED light adj emitting adj2 (diode chip ic die) optical adj2 (chip die ic element)) and (chip ic die) with (window cavity hole via area)
15	BRS	0	"438".ccls. and (LED light adj emitting adj2 (diode chip ic die) optical adj2 (chip die ic element))
16	BRS	8786	"438"/\$.ccls. and (LED light adj emitting adj2 (diode chip ic die) optical adj2 (chip die ic element))
17	BRS	1292	"438"/22,24,26,106,110,116,123,125,126,127.ccls. and (LED light adj emitting adj2 (diode chip ic die) optical adj2 (chip die ic element))
18	BRS	495	"438"/22,24,26,106,110,116,123,125,126,127.ccls. and (LED light adj emitting adj2 (diode chip ic die) optical adj2 (chip die ic element)) and (chip die ic diode) with (window cavit\$3 hole via opening)

	DBs	Time Stamp	Comments	Error Definition
14	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/08/11 17:25		
15	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/08/11 17:26		
16	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/08/11 17:28		
17	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/08/11 17:35		
18	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/08/11 17:47		

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	476	"29"/\$.ccls. and (LED light adj emitting adj2 (diode chip ic die) optical adj2 (chip die ic element)) and (chip die ic diode) with (window cavit\$3 hole via opening)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 21:06